

## **REMARKS**

The Examiner is thanked for the courtesy of the interview that occurred on November 14<sup>th</sup>, 2007. As discussed therein, it is respectfully submitted that the Capote reference does not describe a IC package or a wafer that has a partially cured reflowable (e.g. B-staged) adhesive layer thereon. To summarize the interview, the undersigned pointed out that the hardening of a material is not the same as curing. Specifically, curing requires some type of cross linking. Since Capote does not appear to disclose this feature, it is respectfully submitted that the claims as previously presented are patentable over the art of record. It is believed that the Examiner understood and agreed with that distinction in the interview.

It is noted that a common term used to define the state of the adhesive set forth in independent claims 1 and 35 is that the adhesive is B-staged. In the amendments set forth above, we have proposed adding that language to the claim. If the examiner would prefer the original claim language we would be happy to return the claim language to its previous form.

In view of the foregoing, it is respectfully submitted that all of the pending claims are patentably distinct from the cited art of record for at least this reasons.

If any fees are required in connection with the filing of this response, including any fees required for any required extension of time, such fees may be charged to Deposit Account No. 500388 (Order No. NSC1P131X1). Should the Examiner believe that a telephone conference would expedite the prosecution of this application, the undersigned can be reached at the telephone number set out below.

Respectfully submitted,  
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